

Amendments to the Specification:

Please amend the title beginning on page 1, at lines 1-4 as shown below:

~~MANUFACTURING METHODS AND VACUUM OR HERMETICALLY
PACKAGED MICROMACHINED OR MEMS DEVICES FORMED THEREBY HAVING
SUBSTANTIALLY VERTICAL FEEDTHROUGHS~~

METHOD OF FABRICATING A PACKAGE WITH SUBSTANTIALLY
VERTICAL FEEDTHROUGHS FOR MICROMACHINED OR MEMS DEVICES

Beginning on page 7, line 9, under Brief Description of the Drawings, replace the following paragraphs as follows:

FIGURE 1 is a cross-sectional view of a vacuum packaged semiconductor device manufactured in accordance with one embodiment of a method of the present invention including substantially vertical feedthroughs developed for MEMS fabricated using a dissolved wafer process; ~~and~~

FIGURE 2 is a cross-sectional view of a vacuum packaged semiconductor device manufactured in accordance with a second embodiment of the method[~~[.]~~]; and

FIGURE 3 is a block diagram flow chart illustrating steps for carrying out one embodiment of a method of the present invention.